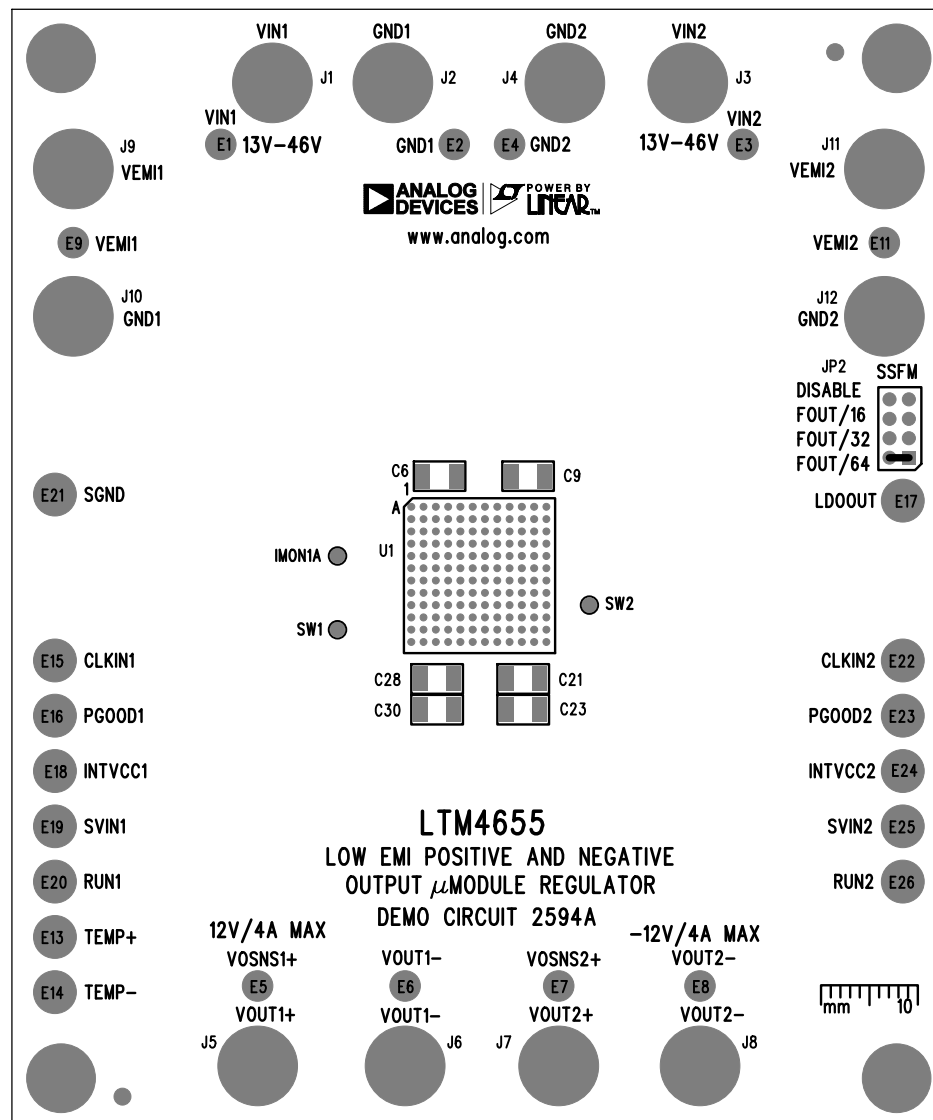
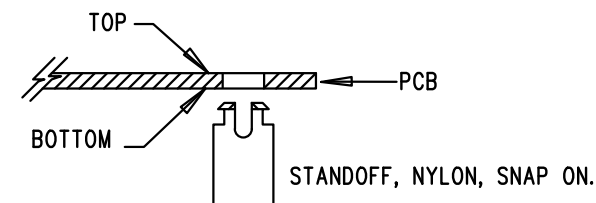


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	3	PRODUCTION	DB	05-09-19



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN.



APPROVALS		ANALOG DEVICES POWER BY LINEAR™		
PCB DES.	LT	FOR ADI CUSTOMER USE ONLY		
APP ENG.	DB	TITLE: TOP ASSEMBLY DRAWING		
		LOW EMI POSITIVE AND NEGATIVE		
		OUTPUT μ MODULE REGULATOR		
		SIZE	IC NO. LTM4655EY	REV. 3
		N/A	DEMO CIRCUIT 2594A	
SCALE = NONE		FILENAME: DC2594A-3.PCB		SHT 1 OF 2